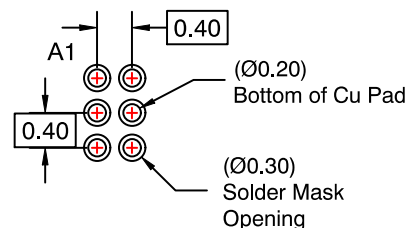
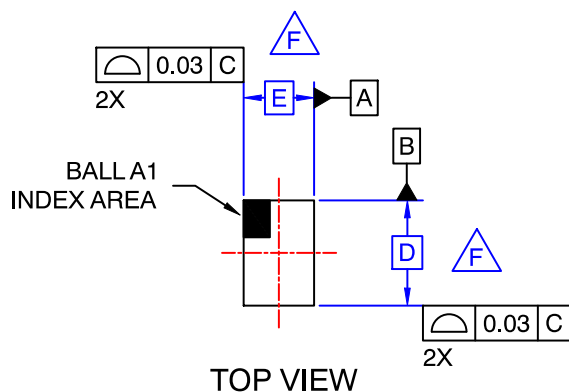
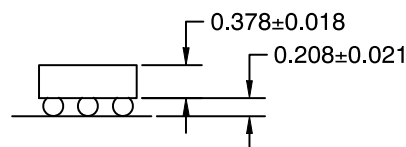
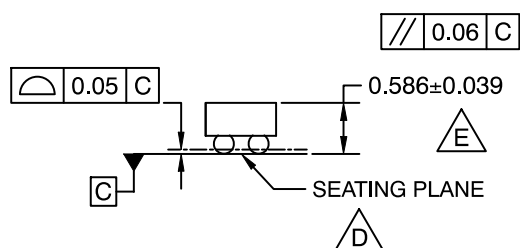


WLCSP6 1.31x0.96x0.586
CASE 567RS
ISSUE O

DATE 30 NOV 2016



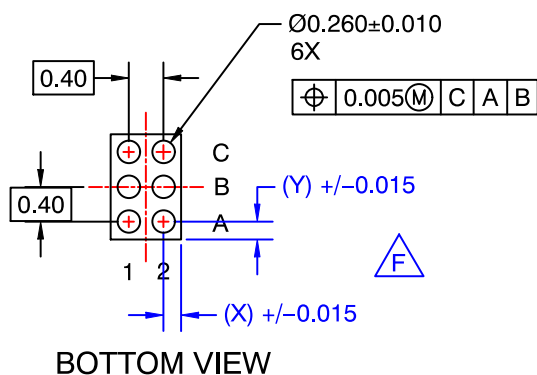
RECOMMENDED LAND PATTERN (NSMD PAD TYPE)



SIDE VIEWS

NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASMEY14.5M, 2009.
- D. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E. PACKAGE TYPICAL HEIGHT IS 586 MICRONS ± 39 MICRONS (547–625 MICRONS).
- F. FOR DIMENSIONS D, E, X, AND Y, SEE PRODUCT DATASHEET.



BOTTOM VIEW

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